### 506167363 07/22/2020

### PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6214100

| SUBMISSION TYPE:      | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT     |

#### **CONVEYING PARTY DATA**

| Name            | Execution Date |
|-----------------|----------------|
| Pei-Yu Huang    | 02/19/2020     |
| Chih-Yuan Hsiao | 11/04/2019     |
| Chiao-Pin Fan   | 07/21/2020     |
| Chi-Wen Pan     | 02/19/2020     |
| Tai-Yu Chen     | 02/19/2020     |
| Chien-Tse Fang  | 11/04/2019     |
| Jih-Ming Hsu    | 02/19/2020     |
| Yun-Ching Li    | 07/07/2020     |

#### **RECEIVING PARTY DATA**

| Name:           | MEDIATEK INC.  |
|-----------------|--|
| Street Address: | No. 1, Dusing Rd. 1st, Science-Based Industrial Park |
| City:           | Hsin-Chu   |
| State/Country:  | TAIWAN   |

#### **PROPERTY NUMBERS Total: 1**

| Property Type       | Number   |
|---------------------|----------|
| Application Number: | 16718099 |

#### **CORRESPONDENCE DATA**

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU

Address Line 1: 5F., NO.389, FUHE RD., YONGHE DIST.,

Address Line 4: NEW TAIPEI CITY, TAIWAN

| ATTORNEY DOCKET NUMBER: | MTKP3338USA |
|-------------------------|-------------|
| NAME OF SUBMITTER:      | SIBYL YU    |
| SIGNATURE:              | /SIBYL YU/  |
| DATE SIGNED:            | 07/22/2020  |

| Total Attachments: 16     |  |
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#### Title of Invention:

METHOD AND APPARATUS OF DYNAMIC THERMAL MANAGEMENT BASED ON SURFACE TEMPERATURES OF PORTABLE DEVICE

| As the below named inventor, I hereby declare that:<br>This declaration is directed to:   |
|---|
| ☐ The attached application, or  |
| ☑ United States application number 16/718,099 filed on 12/17/2019 , or  |
| ☐ PCT international application numberfiled on  |
| The above-identified application was made or authorized to be made by me.   |
| I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.  |
| I hereby acknowledge that any willful false statement made in this declaration is punishable under18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.  |
| In consideration of the payment by MEDIATEK INC. having a postal address of   |
| No. 1, Dusing Rd. 1st, Science-Based Industrial Park, Hsin-Chu 300, Taiwan, R.O.C.  |
| (referred to as "ASSIGNEE"below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.   |
| I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof. |
| I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;  |
| I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal   |
| representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.  |
| Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire  |

Page 1 of 16

inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR (ASSIGNOR)

Inventor:

Pei-Yu Huang

Page 2 of 16

#### Title of Invention:

METHOD AND APPARATUS OF DYNAMIC THERMAL MANAGEMENT BASED ON SURFACE TEMPERATURES OF PORTABLE DEVICE

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| ☐ PCT international application num  | ber   | filed on  | _  |
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| I hereby acknowledge that any willful false sunder18 U.S.C. 1001 by fine or imprisonment   | statement made in this dec<br>nt of not more than five (5)                                    | laration is punishable<br>years, or both.   |    |
| In consideration of the payment by MEDI  | ATEK INC.   | having a postal address   | of |
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| I hereby sell, assign and transfer to ASSIGN the entire right, title and interest in and to an invention as above-identified application and invention by the above application or any cosubstitutes, or extensions thereof, and as to | ny and all improvements wh<br>d, in and to, all Letters Pate<br>entinuations, continuation-ir | hich are disclosed in the<br>ent to be obtained for said<br>n-part, divisions, renewals |    |
| I hereby covenant that no assignment, sale, entered into which would conflict with this as   | agreement or encumbrand ssignment;  | ce has been or will be made or  |    |
| I further covenant that ASSIGNEE will, upon<br>and documents relating to said invention and<br>known and accessible to I and will testify as<br>related thereto and will promptly execute an   | d said Letters Patent and le<br>to the same in any interfer                                   | egal equivalents as may be rence. Iitigation proceeding                                 |    |
| representatives any and all papers, instrume maintain, issue and enforce said application equivalents thereof which may be necessary IN WITNESS WHEREOF, I have hereunto s   | , said invention and said Lo  | etters Patent and said<br>he proposes thereof   |    |
| Note: An application data sheet (PTO/SB/14 inventive entity, must accompany this form.   | or equivalent), including n<br>Use this form for <u>each add</u>                              | naming the entire<br>litional inventor.   |    |

Page 3 of 16

NPO#MTK-P3338-USA:0 CUST#MTKI-18-0207US

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chih-Yuan Hsiao

Date:

2019.11,4

Signature:

Chih - Yuan Hsiao

Page 4 of 16

F#NPO-P0002E-US1201 DSB0-108U013005

NPO#MTK-P3338-USA:0 CUST#MTKI-18-0207US

#### Title of Invention:

METHOD AND APPARATUS OF DYNAMIC THERMAL MANAGEMENT BASED ON SURFACE TEMPERATURES OF PORTABLE DEVICE

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| United States application number  | 16/718,099   | filed on 12/17/2019   | , or     |
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| I believe that I am the original inventor or an application.  | original joint inventor of a   | claimed invention in the  |          |
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| I hereby sell, assign and transfer to ASSIGN the entire right, title and interest in and to an invention as above-identified application and invention by the above application or any consubstitutes, or extensions thereof, and as to | y and all improvements w.<br>l, in and to, all Letters Pato<br>ntinuations, continuation-i | hich are disclosed in the<br>ent to be obtained for said<br>n-part, divisions, renewals | IEE      |
| I hereby covenant that no assignment, sale, entered into which would conflict with this as  | agreement or encumbran<br>signment;  | ce has been or will be made   | or       |
| I further covenant that ASSIGNEE will, upon<br>and documents relating to said invention and<br>known and accessible to I and will testify as<br>related thereto and will promptly execute and   | d said Letters Patent and I<br>to the same in any interfe                                  | egal equivalents as may be rence. litigation proceeding                                 | :ts      |
| representatives any and all papers, instrume maintain, issue and enforce said application, equivalents thereof which may be necessary IN WITNESS WHEREOF, I have hereunto se  | said invention and said L<br>or desirable to carry out t                                   | etters Patent and said  |          |
| Note: An application data sheet (PTO/SB/14 inventive entity, must accompany this form. U  | or equivalent), including r<br>Jse this form for <u>each add</u>                           | naming the entire<br>litional inventor.   |          |

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chiao-Pin Fan

Date:

July 21, 2020

Signature: Chiao Pin Fan

r:

Page 6 of 16

F#NPO-P0002E-US1201 DSB0-108U013005

NPO#MTK-P3338-USA:0 CUST#MTKI-18-0207US

### Title of Invention:

### METHOD AND APPARATUS OF DYNAMIC THERMAL MANAGEMENT BASED ON SURFACE TEMPERATURES OF PORTABLE DEVICE

| As the below named inventor, I hereby dec<br>This declaration is directed to:  | clare that:   |  |
|--|---|--|
| ☐ The attached application, or   |   |  |
| United States application number   | 16/718,099  | filed on <u>12/17/2019</u> , or  |
| ☐ PCT international application num  | nber  | filed on   |
| The above-identified application was made  | or authorized to be made b  | by me.   |
| I believe that I am the original inventor or a application.  | n original joint inventor of a  | claimed invention in the   |
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| I hereby sell, assign and transfer to ASSIG the entire right, title and interest in and to a invention as above-identified application ar invention by the above application or any c substitutes, or extensions thereof, and as t | iny and all improvements which, in and to, all Letters Pate<br>ontinuations, continuation-i | nich are disclosed in the<br>ent to be obtained for said<br>n-part, divisions, renewals, |
| I hereby covenant that no assignment, sale entered into which would conflict with this a   | e, agreement or encumbrand<br>assignment;   | ce has been or will be made or   |
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| representatives any and all papers, instrummaintain, issue and enforce said applicatio equivalents thereof which may be necessa IN WITNESS WHEREOF, I have hereunto  | n, said invention and said L<br>ry or desirable to carry out t                              | etters Patent and said<br>he proposes thereof.   |
| Note: An application data sheet (PTO/SB/1 inventive entity, must accompany this form   | 4 or equivalent), including r . Use this form for each add                                  | naming the entire<br>litional inventor.  |

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chi-Wen Pan

Date: 2020.02.19

Signature:

Chick Run

Page 8 of 16

F#NPO-P0002E-US1201 DSB0-108U013005

NPO#MTK-P3338-USA:0 CUST#MTKI-18-0207US

#### Title of Invention:

METHOD AND APPARATUS OF DYNAMIC THERMAL MANAGEMENT BASED ON SURFACE TEMPERATURES OF PORTABLE DEVICE

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Page 9 of 16

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Tai-Yu Chen

Signature:

Page 10 of 16

F#NPO-P0002E-US1201 DSB0-108U013005

NPO#MTK-P3338-USA:0 CUST#MTKI-18-0207US

### Title of Invention:

### METHOD AND APPARATUS OF DYNAMIC THERMAL MANAGEMENT BASED ON SURFACE TEMPERATURES OF PORTABLE DEVICE

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chien-Tse Fang

Date:

2019/11/04

Signature:

Page 12 of 16

F#NPO-P0002E-US1201 DSB0-108U013005

NPO#MTK-P3338-USA:0 CUST#MTKI-18-0207US

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Page 13 of 16

NPO#MTK-P3338-USA:0 CUST#MTKI-18-0207US

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Jih-Ming Hsu

Date:

2020, 02,19

Signature:

Jih-Ming Hsy

Page 14 of 16

F#NPO-P0002E-US1201 DSB0-108U013005

NPO#MTK-P3338-USA:0 CUST#MTKI-18-0207US

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Page 15 of 16

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NPO#MTK-P3338-USA:0 CUST#MTKI-18-0207US

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Yun-Ching Li

Date:

2020.7.7

NPO#MTK-P3338-USA:0

CUST#MTK1-18-0207US

Signature: Jun Cliny Li

Page 16 of 16

F#NPO-P0002E-US1201 DSB0-108U013005

**PATENT** REEL: 053285 FRAME: 0841 **RECORDED: 07/22/2020**